



J. Hsu 4-5

**IN THE UNITED STATES
PATENT AND TRADEMARK OFFICE**

Supplemental Declaration under 37 CFR 1.67

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am an original, first and joint inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled **Improved Layers Of Group III - Nitride Semiconductor** the specification of which

☐ is attached hereto

OR

☒ was filed on December 12, 2003 as Application Serial Number 10/735,191.

I hereby state that I have reviewed and understand the contents of the above-identified specification including the claims as amended by a preliminary amendment filed Dec. 12, 2003.

I acknowledge the duty to disclose all information known to me which is material to patentability as defined in Title 37, Code of Federal Regulations, 1.56.

I hereby claim foreign priority benefits under Title 35, United States Code, 119 of any foreign application(s) for patent or inventor's certificate listed below and have also identified below any foreign application for patent or inventor's certificate having a filing date before that of the application on which priority is claimed:

None

I hereby claim the benefit under Title 35, United States Code, 120 of any United States application(s) listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code, 112, I acknowledge the duty to disclose all information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations, 1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application:

U.S. Patent Application No. 10/179,806 filed June 25, 2002 by Julia W.P. Hsu et al

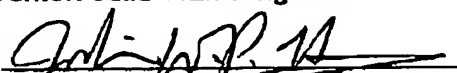
I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States

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Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of 1st joint inventor: Julia Wan-Ping Hsu

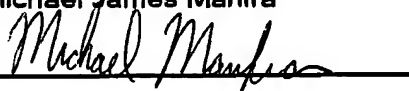
Inventor's signature  Date 10/1/2004

Residence: Albuquerque, Bernalillo, New Mexico

Citizenship: United States of America

Post Office Address: 7200 Torin Dr. NE
Albuquerque, NM 87122

Full name of 2nd inventor: Michael James Manfra

Inventor's signature  Date 1/14/05

Residence: Chatham, Morris, New Jersey

Citizenship: United States of America

Post Office Address: 420 River Road, apt. E12
Chatham, NJ 07928